

40V N-Channel Trench MOSFET(Preliminary)

General Description

Trench Power technology

Maximum Junction-to-Ambient

- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

 V_{DS} 40V I_{D} (at V_{GS} =10V) 120A

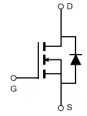
$$\begin{split} R_{DS(ON)} \; (at \; V_{GS} \!=\! 10V) & < 3.5 m\Omega \\ R_{DS(ON)} \; (at \; V_{GS} \!=\! 4.5V) & < 4.7 m\Omega \end{split}$$

100% UIS Tested









Part Number	Package Type	Form	Marking	
TTP120N04AT	TO-220	Tube	120N04AT	

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	40	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current B	T _C =25°C		105	Δ
Continuous Drain Current B	T _C =100°C		85	А
Pulsed Drain Current ^A		I _{DM}	360	А
Avalanche Current ^A		I _{AS}	35	А
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	138.4	mJ
Power Dissipation ^C	T _C =25°C	P _D	143	W
Power Dissipation	T _C =100°C	' D	82	W
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 175	°C
Thermal Characteristics				
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Case Steady-State		$R_{\Theta JC}$	1.1	00.004
				°C/W

100

 $R_{\Theta JA}$

Steady-State



Comple al		Parameter Conditions		Value			l
Symbol	Parameter			Min	Тур	Max	Units
STATIC P	ARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		40			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V	T _J =25°C			1	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	T _J =100°C			25 ±100	nA
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{V}, V_{GS} = \pm 20V$ $V_{DS} = V_{GS}, I_{D} = 250\mu A$		1	1.7	2.4	V
V GS(th)	Odie Tilleshold Voltage	$V_{GS} = V_{GS}, I_D = 230 \mu A$ $V_{GS} = 10 V, I_D = 30 A$		'	2.7	3.5	mΩ
R _{DS(ON)} Static Drain-Source On-Resis	Static Drain-Source On-Resistance	$V_{GS} = 4.5V, I_D = 30A$			3.6	4.7	mΩ
9 _{FS}	Forward Transconductance	$V_{DS} = 10V, I_{D} = 20A$			36.4		S
V _{SD}	Diode Forward Voltage	I _S =30A, V _{GS} =0V				1	V
I _S	Maximum Body-Diode Continuous Curre					105	A
	PARAMETERS						
C _{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 20V, f = 1MH_Z$			5331		pF
C _{oss}	Output Capacitance				987		
C _{rss}	Reverse Transfer Capacitance				378		
SWITCHII	NG PARAMETERS		•			•	
Q _g (10V)	Total Gate Charge	V _{GS} =10V,V _{DS} =20V, I _D =60A			132		
Q_{gs}	Gate Source Charge				23		nC
Q_{gd}	Gate Drain Charge				23		
t _{D(on)}	Turn-On Delay Time				27		
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DS} = 20V, I_{D} = 60A,$ $R_{G} = 3\Omega$			11		ns
$T_{D(off)}$	Turn-Off Delay Time				83		
t _f	Turn-Off Fall Time				14		
t _{rr}	Body Diode Reverse Recovery Time	1 200 4:1:14 400 4			66		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, di/dt =100A/μs			73		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

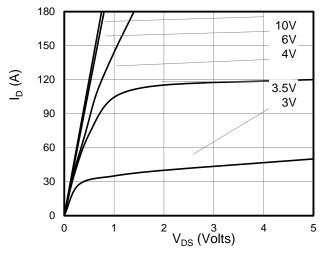


Figure 1: On-Region Characteristics

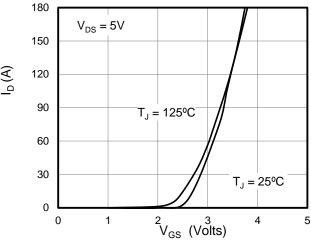


Figure 2: Transfer Characteristics

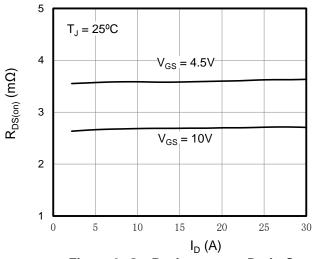


Figure 3: On-Resistance vs. Drain Current

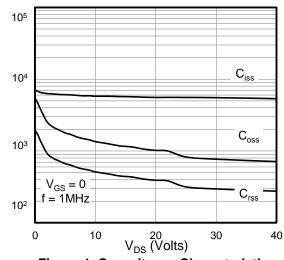


Figure 4: Capacitance Characteristics

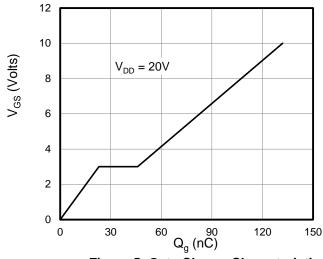


Figure 5: Gate Charge Characteristics

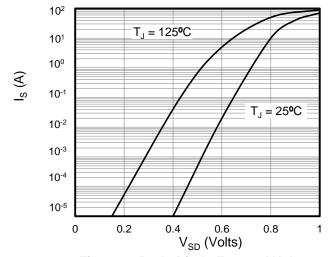


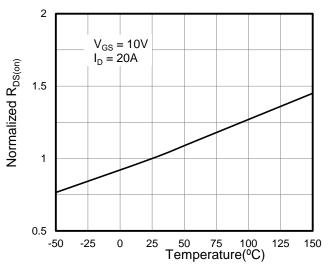
Figure 6: Body Diode Forward Voltage

Capacitance (pF)

 $Z_{\theta, JC}$ Normalized Transient Thermal Resistance

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



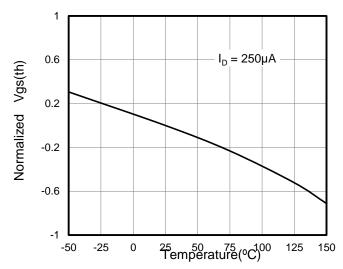
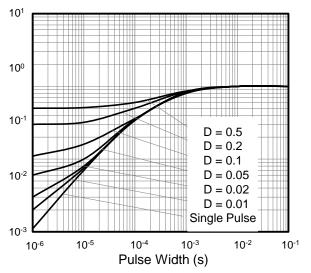


Figure 7: On-Resistance vs. Junction Temperature

Figure 8: Vgs(th) vs. Junction Temperature



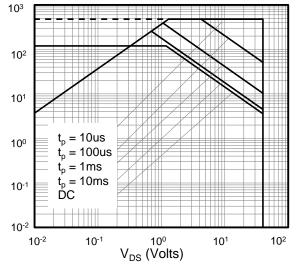


Figure 9: Normalized Transient Thermal Resistance

Figure 10: Safe Operating Area

I_D (Amps)

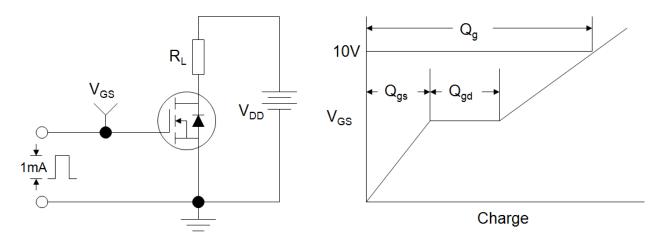


Figure A: Gate Charge Test Circuit and Waveforms

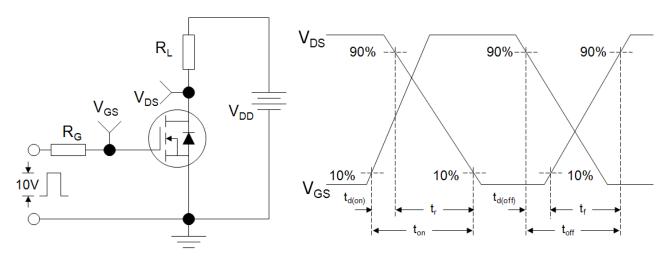


Figure B: Resistive Switching Test Circuit and Waveforms

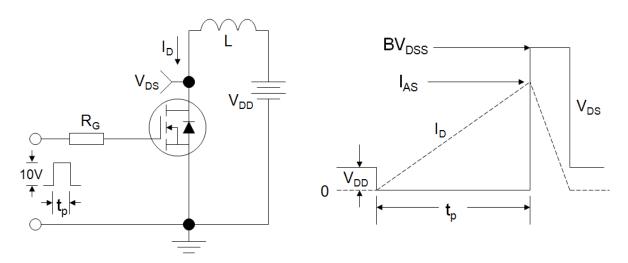
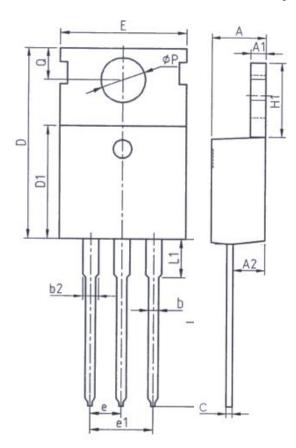
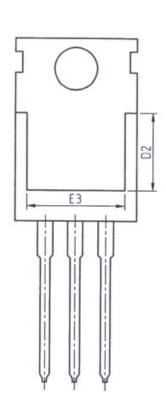


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



TO-220(华羿)





Unit: mm			
Symbol	Min.	Max.	
Α	4. 37	4. 77	
A1	1. 25	1. 45	
A2	2. 20	2. 60	
b	0. 70	0. 95	
b2	1. 17	1. 47	
С	0. 40	0. 65	
D	15. 10	16. 10	
D1	8. 80	9. 40	
D2	5. 50	_	

Unit: mm				
Symbol	Min.	Max.		
E	9. 70	10. 30		
E3	7. 00	ı		
е	2. 54BSC			
e1	5. 08BSC			
H1	6. 25	6. 85		
L	12. 75	13. 80		
L1	_	3. 40		
Р	3. 40	3. 80		
Q	2. 60	3. 00		



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